

DLPF-GP-01D3

Dual differential filter with integrated matching for GreenPeak transceiver

Description

performances.

Datasheet - production data



Features

- Nominal Input / conjugate match to GreenPeak
- Low loss dual-channel differential filter
- Low loss dual-channel common-mode filter
- Small footprint < 1.2 x 3.4 mm²
- Very low profile (< 560 µm after reflow)
- High RF performance
- RF BOM and area reduction

Applications

- 2.45 GHz impedance matched dual-differential filter
- Optimized for GreenPeak GP540 and GP561 circuits
- a. Courtesy of GreenPeak.

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This is information on a product in full production.

The DLPF-GP-01D3 is an ultra miniature dual differential filter tailored for GreenPeak

The DLPF-GP-01D3 integrates also matching

GreenPeak Zigbee/RF4CE RF transceivers. It is using STMicroelectronics IPD technology on nonconductive Glass substrate which optimize RF

network and replaces 16 SMD components. Matching impedance has been customized for

Zigbee/RF4CE RF transceivers.



1 Absolute maximum ratings

Symbol	Parameter		Value		
Symbol			Тур.	Max.	Unit
P _{IN}	Input Power RFIN			20	dBm
V _{ESD}	ESD Ratings MIL STD883C (HBM:C=100 pF, R=1.5 k Ω , Air discharge)	800			V
	ESD ratings machine model (MM: C=200 pF, R=25 $\Omega,$ L=500 nH)	550			V
T _{OP}	Operating temperature	-40		+80	°C

Table 1. Absolute maximum ratings (limiting value)



2 Electrical characteristics

Symbol	Parameter		Value			
			Тур.	Max.	Unit	
Z _{OUT}	Nominal differential output impedance	-	Conjugate match to GreenPeak IC	-	Ω	
Z _{IN}	Nominal differential input impedance	-	100	-	Ω	

Table 2. Impedances

Table 3. RF performance

Symbol	Parameter	Tast condition	Value			Unit
		rest condition	Min.	Тур.	Max.	onit
T _{OP}	Operating temperature	ture -			+80	°C
f	Frequency range (bandwidth)	/ range (bandwidth) -			2500	MHz
۱ _L	Insertion loss in bandwidth			-1.45	-1.7	dB
R _{L_ANT}	Return loss in bandwidthReturn loss in bandwidth $T_j = 25 \ ^{\circ}C$			-16	-11	dB
R _{L_IC}				-15	-10.5	dB
2f0	2f0 attenuation			-41	-37	dB
3f0	3f0 attenuation			-34	-28	dB



2.1 RF measurements (on board)









Figure 7. Return loss on IC side (dB)





Package mechanical data 3

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK[®] is an ST trademark.



Figure 8. Mechanical specifications (bump view)





Figure 9. Layout recommendations

Dimensions (distances) from center pad to center pad (filter GP chip) shall be respected as much as possible in order to avoid any deviation in performances.







No extra components required thanks to DLPF-GP-01D3.



Figure 14. Tape and reel specification



Note:

The dimensions shown on this proposed drawing are for illustrative purpose. Dimensions from actual carrier may vary slightly

More information is available in the application notes AN2348: "Flip Chip: Package description and recommendations for use".



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4 Ordering information

Part number	Marking	Weight	Base qty	Delivery mode
DLPF-GP-01D3 SW		4.43 mg	5000	Tape and reel

5 Revision history

Date	Revision	Changes
10-Oct-2014	1	Initial release.



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